

## Complementary N & P-Channel Power MOSFET

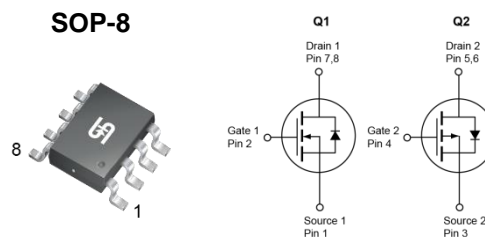
### FEATURES

- Low gate charge for fast power switching
- 100% UIS and  $R_{\theta}$  tested
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

### APPLICATIONS

- Building technologies
- DC Fan
- Motor drives

KEY PERFORMANCE PARAMETERS			
PARAMETER	TYPE	VALUE	UNIT
$V_{DS}$	Q1	60	V
	Q2	-60	
$R_{DS(on)}$ (max)	Q1	$V_{GS} = 10V$	103
		$V_{GS} = 4.5V$	122
	Q2	$V_{GS} = -10V$	180
		$V_{GS} = -4.5V$	220
$Q_g$	Q1	4.4	nC
	Q2	4.6	



**Note:** MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ unless otherwise noted)				
PARAMETER	SYMBOL	Q1	Q2	UNIT
Drain-Source Voltage	$V_{DS}$	60	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current	$I_D$	$T_C = 25^\circ C$	5	-4
		$T_A = 25^\circ C$	2.5	-2
Pulsed Drain Current (Note 1)	$I_{DM}$	20	-16	A
Single Pulse Avalanche Current (Note 2)	$I_{AS}$	6.8	-7	A
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	6.9	7.4	mJ
Total Power Dissipation	$P_D$	$T_C = 25^\circ C$	5.7	5.7
		$T_C = 125^\circ C$	1.1	1.1
Total Power Dissipation	$P_D$	$T_A = 25^\circ C$	1.4	1.4
		$T_A = 125^\circ C$	0.3	0.3
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	- 55 to +150		$^\circ C$

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	MAXIMUM	UNIT
Thermal Resistance – Junction to Case	$R_{\theta JC}$	22	$^\circ C/W$
Thermal Resistance – Junction to Ambient	$R_{\theta JA}$	88	

**Thermal Performance Note:**  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design. The  $R_{\theta JA}$  limit presented here is based on mounting on a 1 in<sup>2</sup> pad of 2 oz copper.

**ELECTRICAL SPECIFICATIONS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	TYPE	MIN	TYP	MAX	UNIT		
<b>Static</b>									
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	$BV_{DSS}$	Q1	60	--	--	V		
	$V_{GS} = 0V, I_D = -250\mu A$		Q2	-60	--	--			
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu A$	$V_{GS(TH)}$	Q1	1.2	1.8	2.5	V		
	$V_{GS} = V_{DS}, I_D = -250\mu A$		Q2	-1	-1.5	-2.5			
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	$I_{GSS}$	Q1	--	--	$\pm 100$	nA		
	$V_{GS} = \pm 20V, V_{DS} = 0V$		Q2	--	--	$\pm 100$	nA		
Drain-Source Leakage Current	$V_{GS} = 0V, V_{DS} = 60V$	$I_{DSS}$	Q1	--	--	1	$\mu A$		
	$V_{GS} = 0V, V_{DS} = -60V$		Q2	--	--	-1			
Drain-Source On-State Resistance <small>(Note 3)</small>	$V_{GS} = 10V, I_D = 2.5A$	$R_{DS(on)}$	Q1	--	74	103	m $\Omega$		
	$V_{GS} = 4.5V, I_D = 2.3A$			--	86	122			
	$V_{GS} = -10V, I_D = -2A$		Q2	--	135	180			
	$V_{GS} = -4.5V, I_D = -1.7A$			--	170	220			
Forward Transconductance <small>(Note 3)</small>	$V_{DS} = 10V, I_D = 2.5A$	$g_{fs}$	Q1	--	10	--	S		
	$V_{DS} = -10V, I_D = -2A$		Q2	--	5	--			
<b>Dynamic</b> <small>(Note 4)</small>									
Total Gate Charge	Q1 $V_{DS} = 30V, I_D = 2.5A$ Q2 $V_{DS} = -30V, I_D = -2A$	$Q_{g(VGS=10V)}$	Q1	--	9.4	--	nC		
Total Gate Charge			Q2	--	9	--			
		Gate-Source Charge	$Q_{g(VGS=4.5V)}$	Q1	--	4.4		--	
Q2				--	4.6	--			
Gate-Drain Charge		$Q_{gs}$	Q1	--	1.8	--			
			Q2	--	1.2	--			
Input Capacitance		Q1 $V_{GS} = 0V, V_{DS} = 30V$	$Q_{gd}$	Q1	--	2.3		--	pF
				Q2	--	2.4		--	
Output Capacitance	f = 1.0MHz Q2	$C_{iss}$	Q1	--	527	--			
			Q2	--	436	--			
Reverse Transfer Capacitance	f = 1.0MHz Q1	$C_{oss}$	Q1	--	31	--			
			Q2	--	32	--			
Gate Resistance	f = 1.0MHz Q1	$C_{rss}$	Q1	--	4	--			
			Q2	--	11	--			
Turn-On Delay Time	Q1 $V_{GS} = 10V, V_{DS} = 30V,$ $I_D = 2.5A, R_G = 2\Omega$	$R_g$	Q1	0.5	1.8	3.6	$\Omega$		
			Q2	5	17	34			
<b>Switching</b> <small>(Note 4)</small>									
Turn-On Delay Time	Q1 $V_{GS} = 10V, V_{DS} = 30V,$ $I_D = 2.5A, R_G = 2\Omega$	$t_{d(on)}$	Q1	--	5	--	ns		
			Q2	--	3.4	--			
Turn-On Rise Time	Q2 $V_{GS} = -10V, V_{DS} = -30V,$ $I_D = -2A, R_G = 2\Omega$	$t_r$	Q1	--	21	--			
			Q2	--	21	--			
Turn-Off Delay Time	Q1 $V_{GS} = 10V, V_{DS} = 30V,$ $I_D = 2.5A, R_G = 2\Omega$	$t_{d(off)}$	Q1	--	10	--			
			Q2	--	21	--			
Turn-Off Fall Time	Q2 $V_{GS} = -10V, V_{DS} = -30V,$ $I_D = -2A, R_G = 2\Omega$	$t_f$	Q1	--	17	--			
			Q2	--	26	--			

<b>ELECTRICAL SPECIFICATIONS</b> ( $T_A = 25^\circ\text{C}$ unless otherwise noted)							
PARAMETER	CONDITIONS	SYMBOL	TYPE	MIN	TYP	MAX	UNIT
<b>Source-Drain Diode</b>							
Forward Voltage (Note 3)	$V_{GS} = 0V, I_S = 2.5A$	$V_{SD}$	Q1	--	--	1	V
	$V_{GS} = 0V, I_S = -2A$		Q2	--	--	-1	
Reverse Recovery Time	Q1 $I_S = 2.5A, di/dt = 100A/\mu s$	$t_{rr}$	Q1	--	14	--	ns
			Q2	--	11	--	
Reverse Recovery Charge	Q2 $I_S = -2A, di/dt = 100A/\mu s$	$Q_{rr}$	Q1	--	10	--	nC
			Q2	--	6	--	

**Notes:**

1. Current limited by package.
2. Q1 :  $L = 0.3mH, V_{GS} = 10V, V_{DD} = 30V, R_G = 25\Omega, I_{AS} = 6.8A$ , Starting  $T_J = 25^\circ\text{C}$   
 Q2 :  $L = 0.3mH, V_{GS} = -10V, V_{DD} = -30V, R_G = 25\Omega, I_{AS} = -7A$ , Starting  $T_J = 25^\circ\text{C}$
3. Pulse test: Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Switching time is essentially independent of operating temperature.

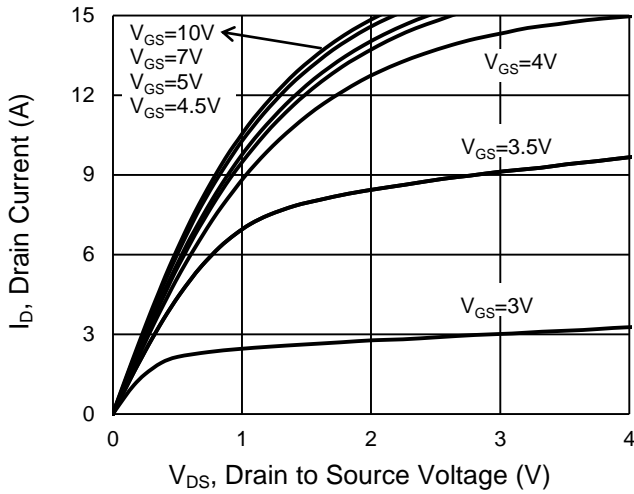
**ORDERING INFORMATION**

ORDERING CODE	PACKAGE	PACKING
TSM8588CS RLG	SOP-8	2,500pcs / 13" Reel

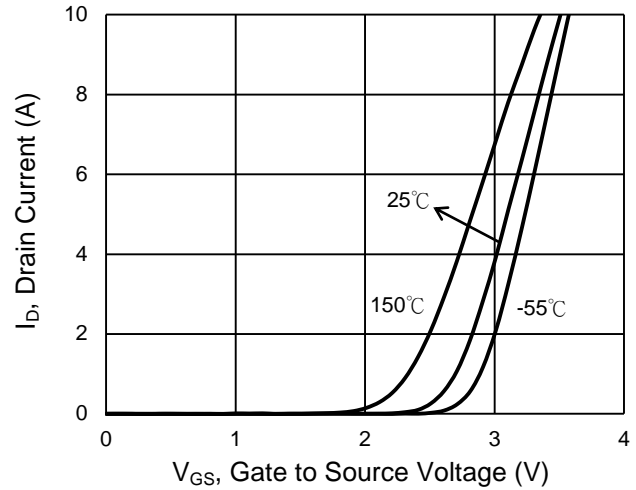
**CHARACTERISTICS CURVES (Q1 N-Channel)**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

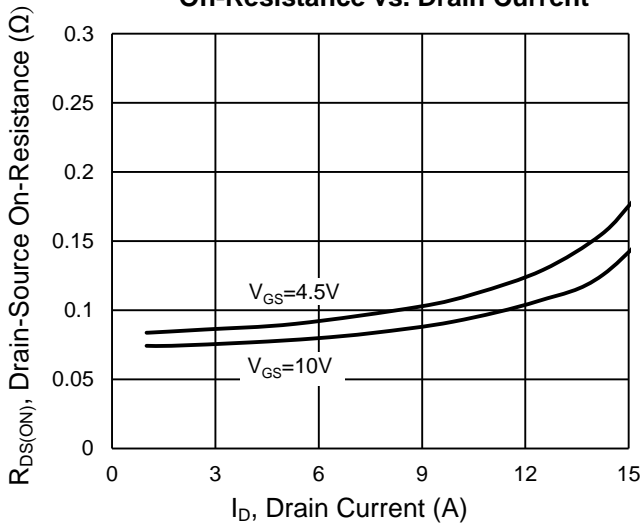
**Output Characteristics**



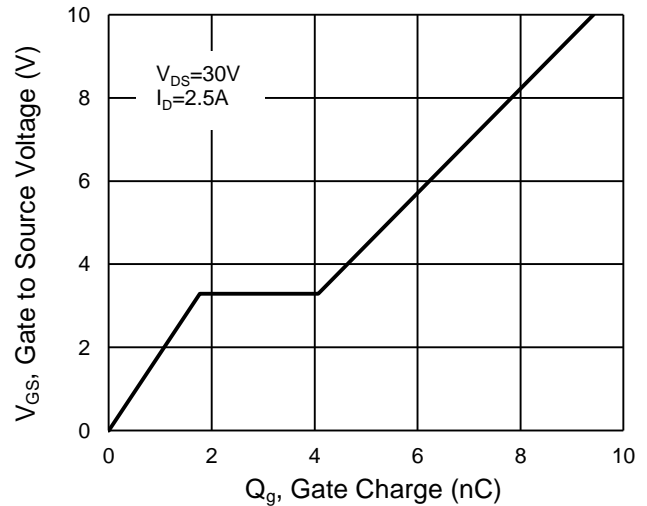
**Transfer Characteristics**



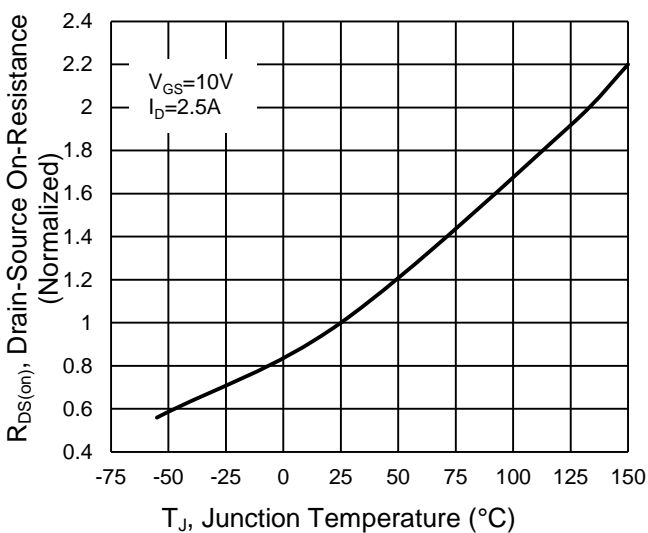
**On-Resistance vs. Drain Current**



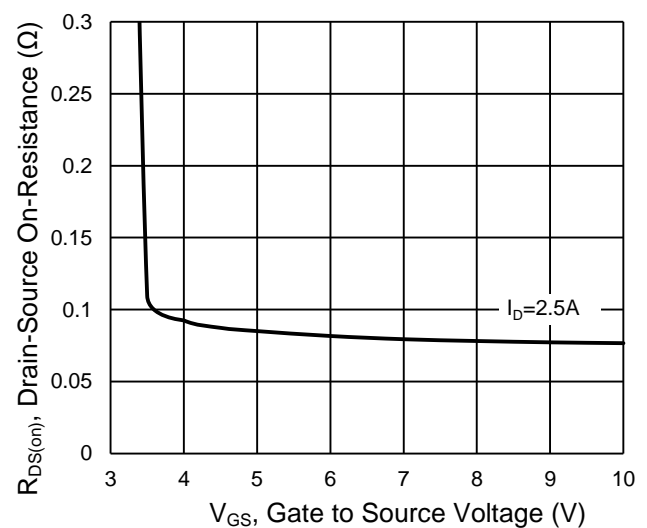
**Gate-Source Voltage vs. Gate Charge**



**On-Resistance vs. Junction Temperature**

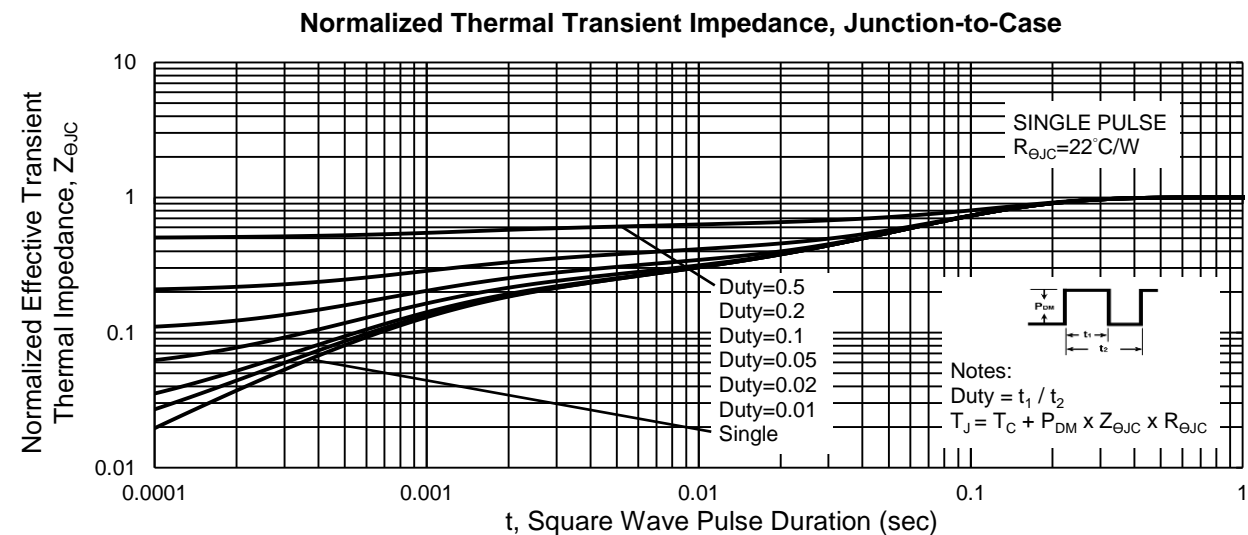
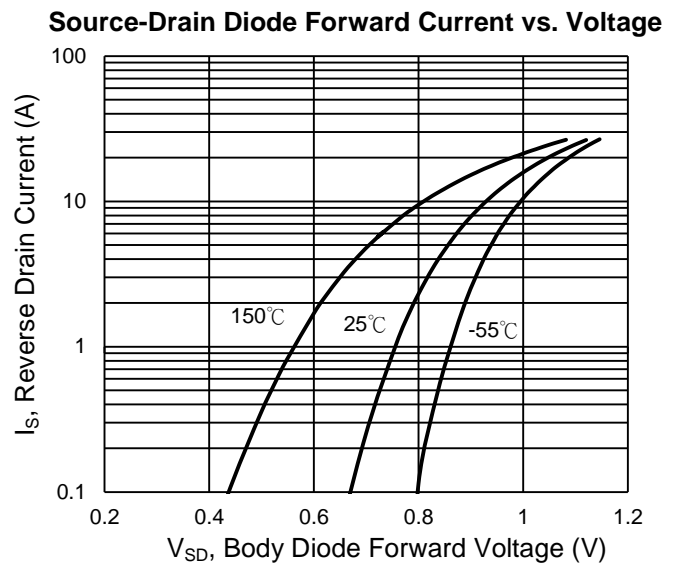
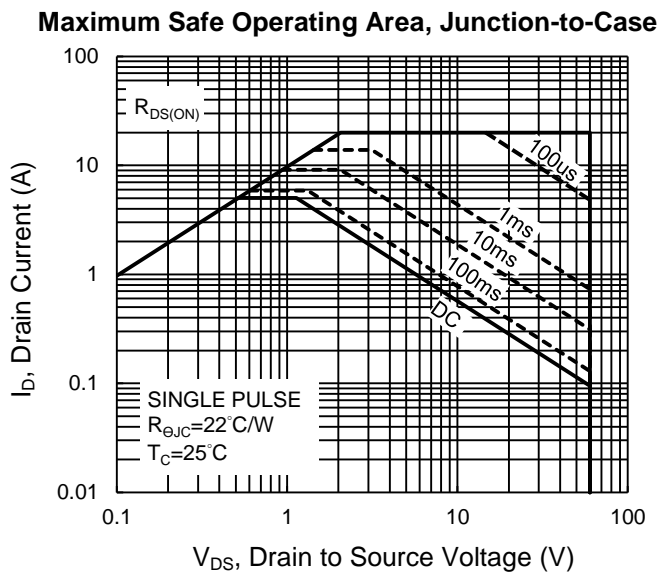
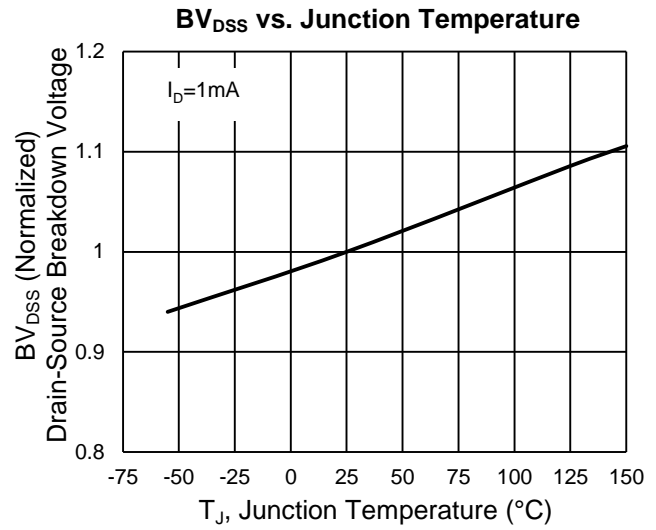
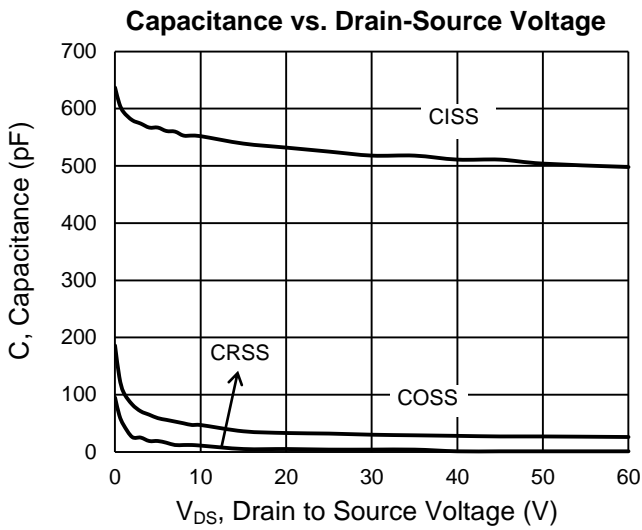


**On-Resistance vs. Gate-Source Voltage**



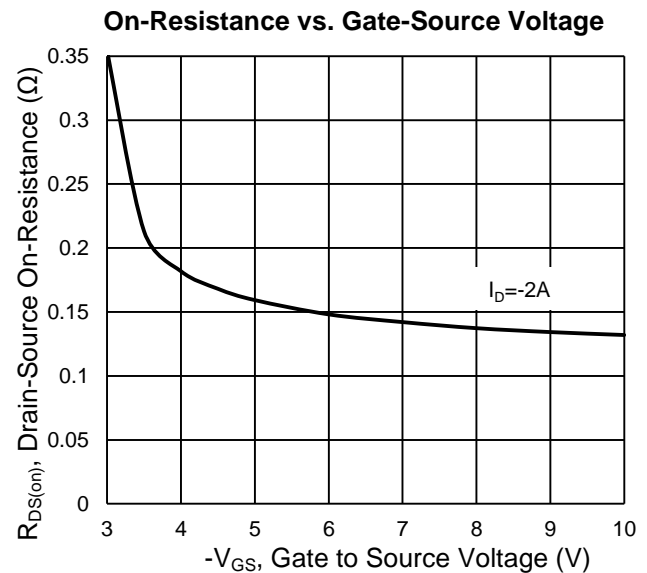
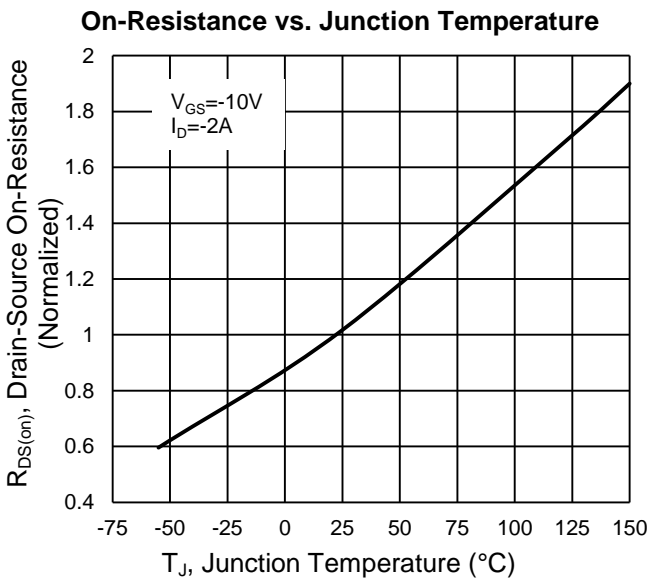
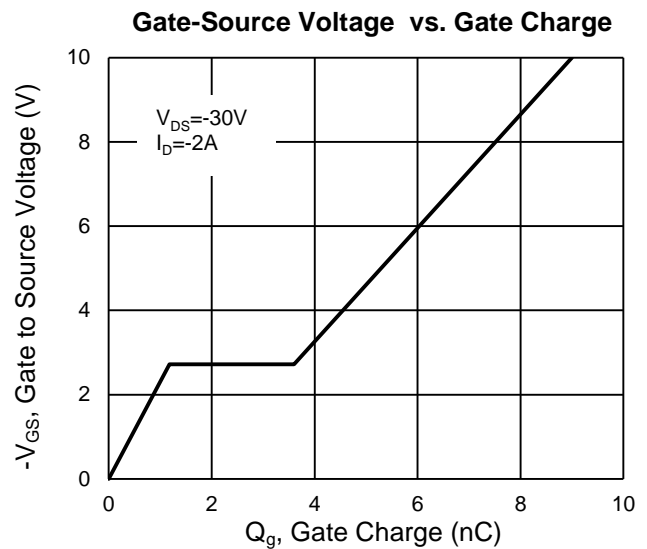
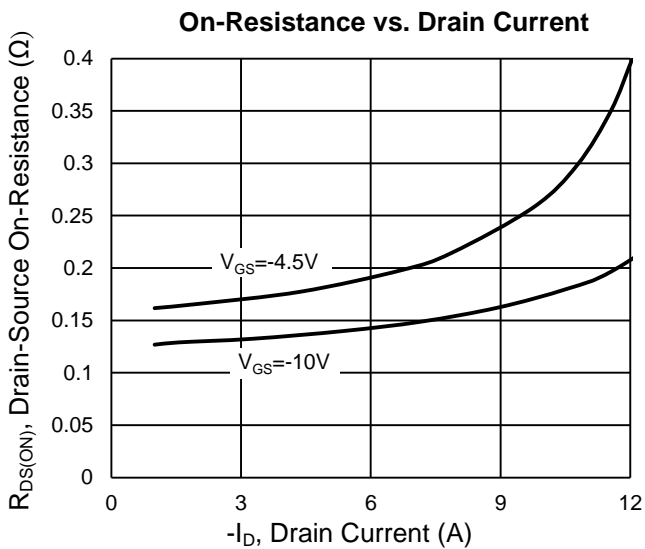
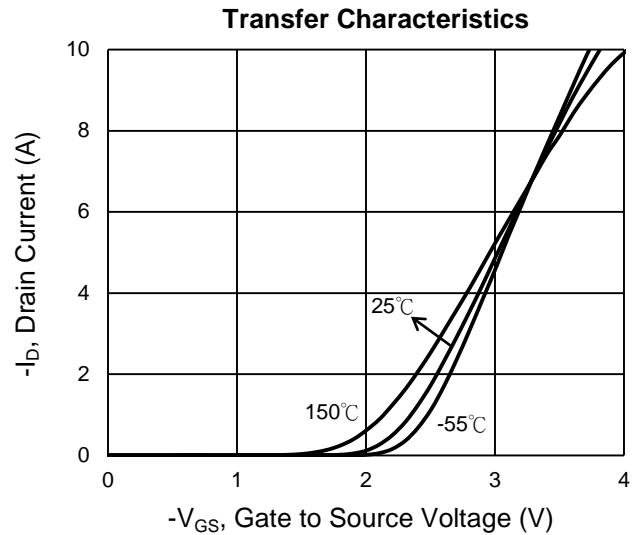
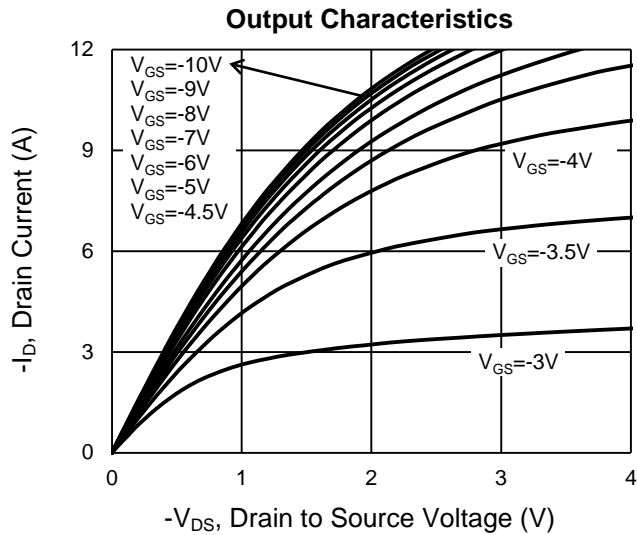
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)



**CHARACTERISTICS CURVES (Q2 P-Channel)**

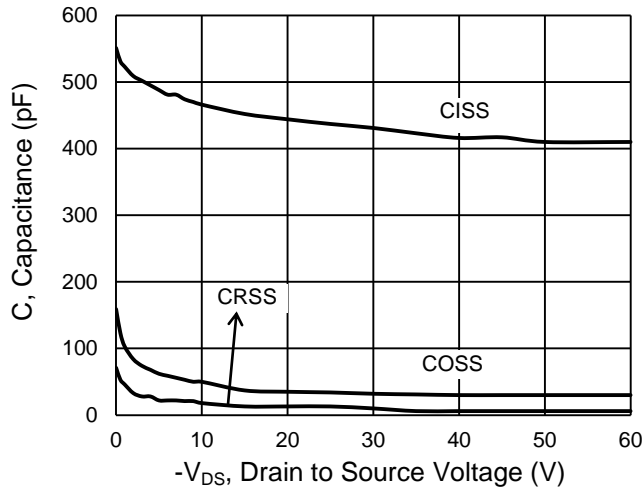
( $T_A = 25^\circ\text{C}$  unless otherwise noted)



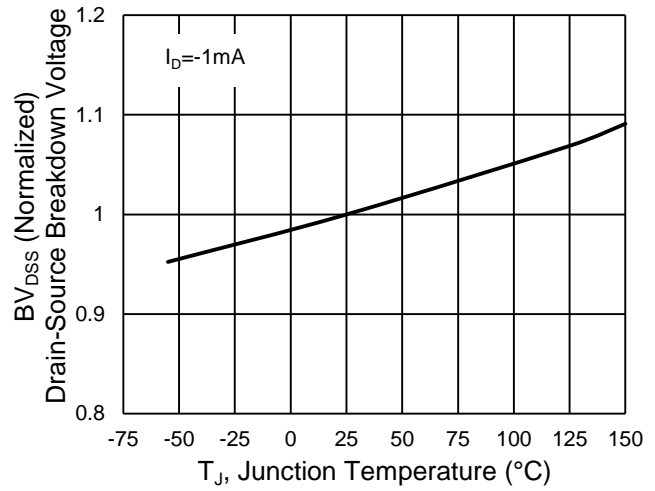
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

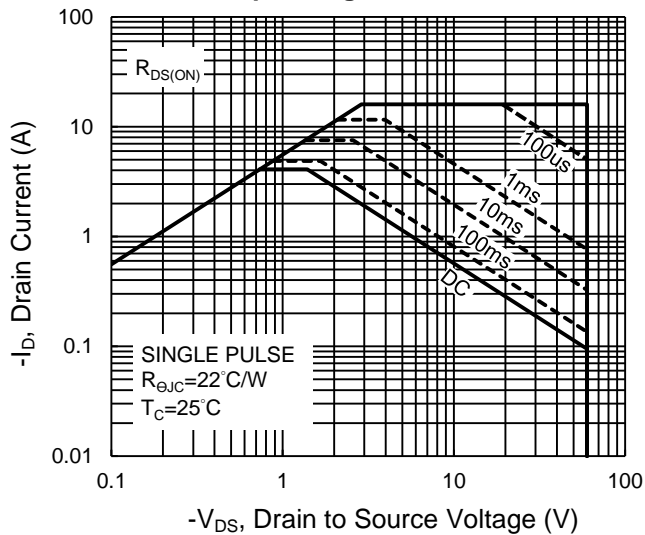
**Capacitance vs. Drain-Source Voltage**



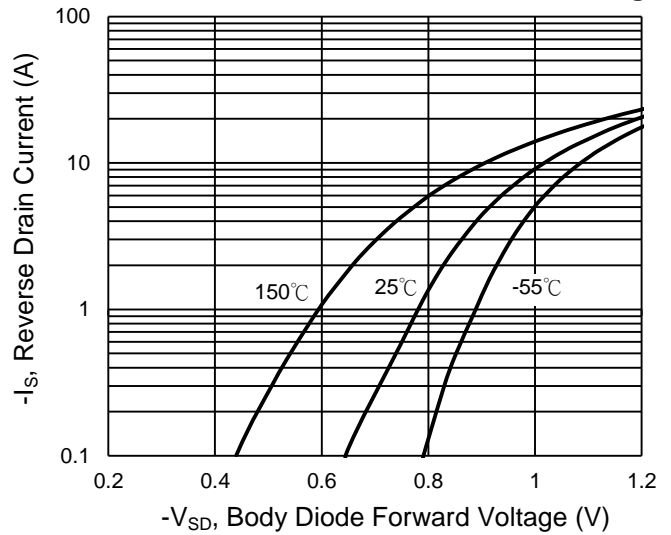
**$BV_{DSS}$  vs. Junction Temperature**



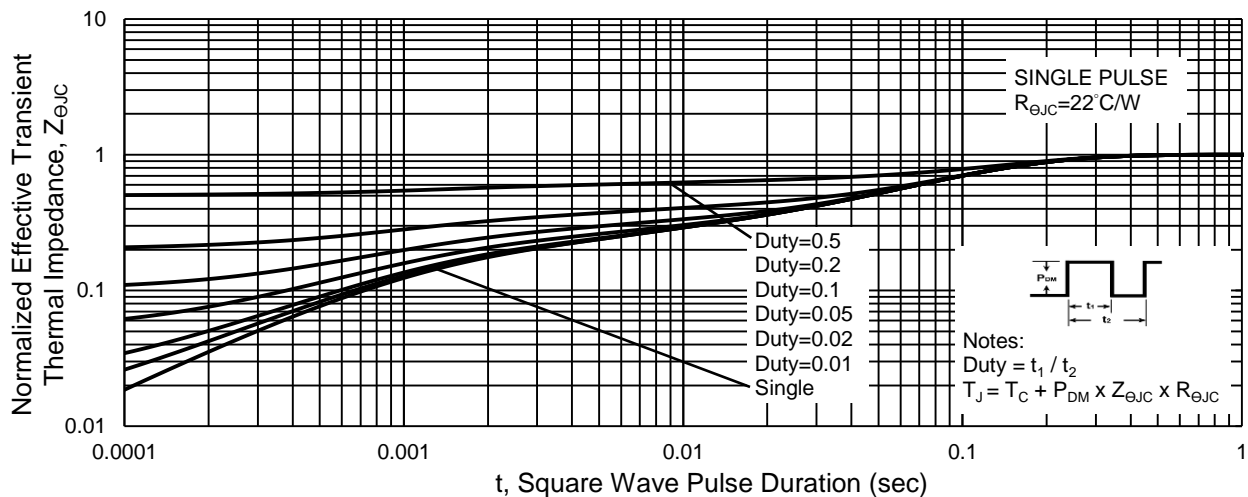
**Maximum Safe Operating Area, Junction-to-Case**



**Source-Drain Diode Forward Current vs. Voltage**

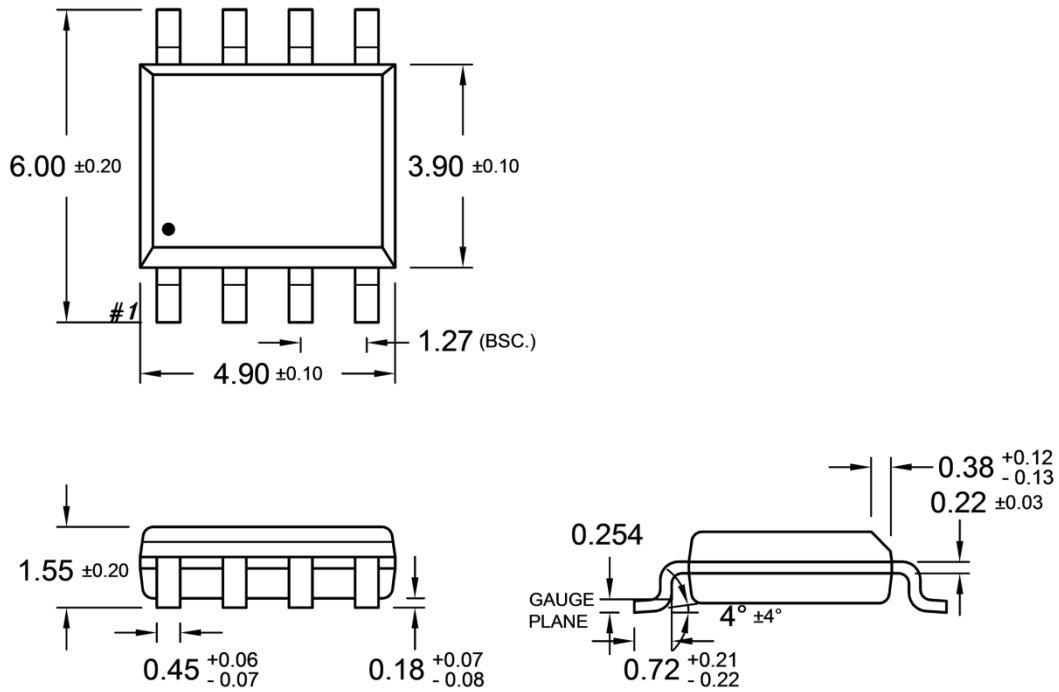


**Normalized Thermal Transient Impedance, Junction-to-Case**

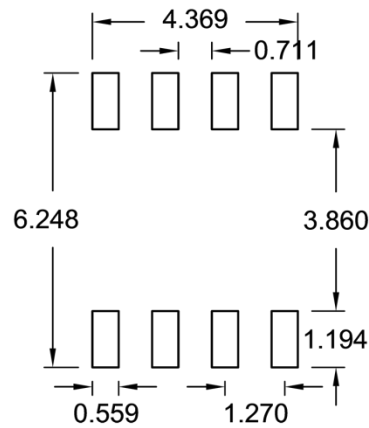


**PACKAGE OUTLINE DIMENSIONS** (Unit: Millimeters)

**SOP-8**



**SUGGESTED PAD LAYOUT** (Unit: Millimeters)



**MARKING DIAGRAM**



- Y** = Year Code
- WW** = Week Code (01~52)
- L** = Lot Code (1~9,A~Z)
- F** = Factory Code



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